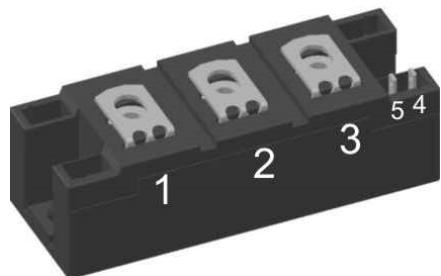


Thyristor \ Diode Module

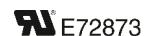
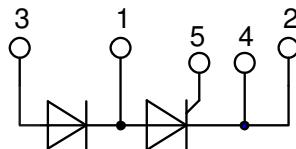
 $V_{RRM} = 2 \times 1800 \text{ V}$
 $I_{TAV} = 200 \text{ A}$
 $V_T = 1,12 \text{ V}$

Phase leg

Part number

MCMA200PD1800YB


Backside: isolated

Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al₂O₃-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: Y4

- Isolation Voltage: 4800 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Disclaimer Notice

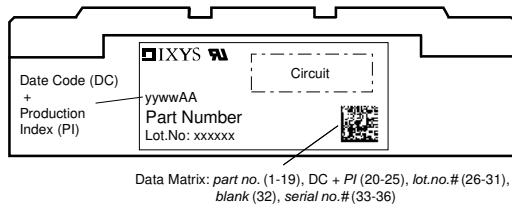
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Thyristor

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1900	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1800	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1800 V$ $V_{R/D} = 1800 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		300 10	μA mA
V_T	forward voltage drop	$I_T = 200 A$ $I_T = 400 A$ $I_T = 200 A$ $I_T = 400 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1,17 1,40 1,12 1,41	V V
I_{TAV}	average forward current	$T_C = 85^\circ C$	$T_{VJ} = 140^\circ C$		200	A
$I_{T(RMS)}$	RMS forward current	180° sine			315	A
V_{TO}	threshold voltage	r_T slope resistance } for power loss calculation only	$T_{VJ} = 140^\circ C$		0,83	V
	slope resistance				1,43	$m\Omega$
R_{thJC}	thermal resistance junction to case				0,17	K/W
R_{thCH}	thermal resistance case to heatsink			0,09		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		680	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 140^\circ C$ $V_R = 0 V$		6,00 6,48 5,10 5,51	kA kA
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 140^\circ C$ $V_R = 0 V$		180,0 174,7 130,1 126,3	kA^2s kA^2s kA^2s kA^2s
C_J	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	273		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$ $t_p = 500 \mu s$	$T_C = 140^\circ C$		120 60 8	W W W
P_{GAV}	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 140^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 600 A$ $t_p = 200 \mu s; di_G/dt = 0,5 A/\mu s;$ $I_G = 0,5 A; V_D = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 200 A$			100	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	$T_{VJ} = 140^\circ C$		1000	$V/\mu s$
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		2,5 2,6	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		150 200	mA mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		0,2	V
I_{GD}	gate non-trigger current				10	mA
I_L	latching current	$t_p = 30 \mu s$ $I_G = 0,5 A; di_G/dt = 0,5 A/\mu s$	$T_{VJ} = 25^\circ C$		300	mA
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		200	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0,5 A; di_G/dt = 0,5 A/\mu s$	$T_{VJ} = 25^\circ C$		2	μs
t_q	turn-off time	$V_R = 100 V; I_T = 200 A; V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ C$ $di/dt = 10 A/\mu s; dv/dt = 20 V/\mu s; t_p = 200 \mu s$		150		μs

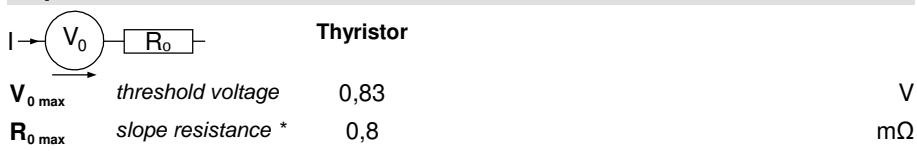
Package Y4

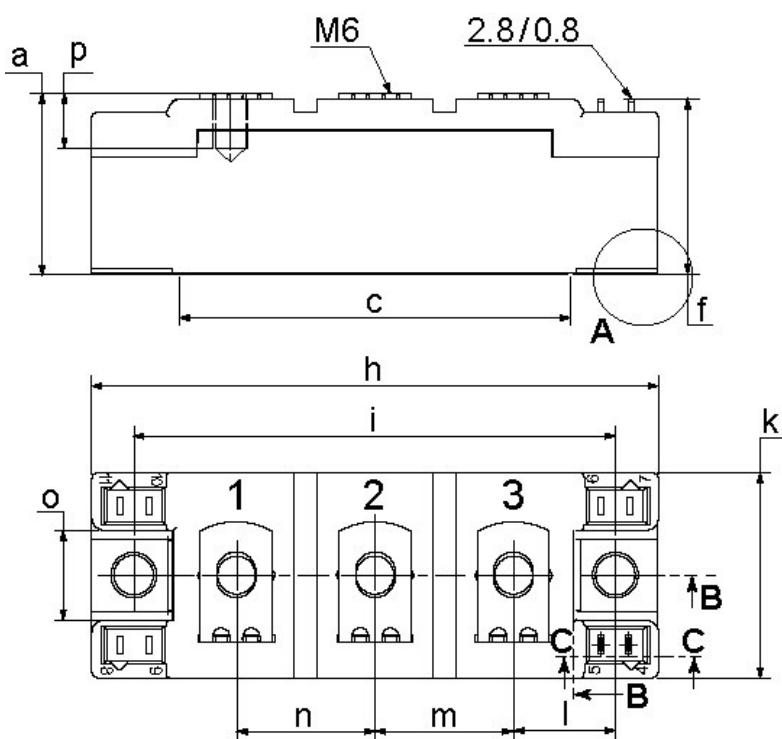
Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per terminal			300	A
T_{VJ}	virtual junction temperature		-40		140	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight				131		g
M_D	mounting torque		2,25		2,75	Nm
M_T	terminal torque		4,5		5,5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	14,0	10,0		mm
$d_{Spb/Apb}$		terminal to backside	16,0	16,0		mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	4800 4000		V V


Part description

M = Module
C = Thyristor (SCR)
M = Thyristor
A = (up to 1800V)
200 = Current Rating [A]
PD = Phase leg
1800 = Reverse Voltage [V]
YB = Y4-M6

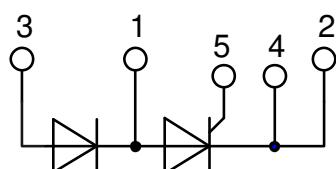
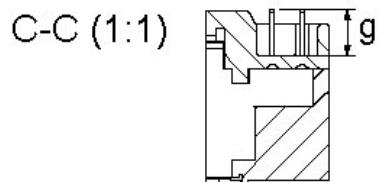
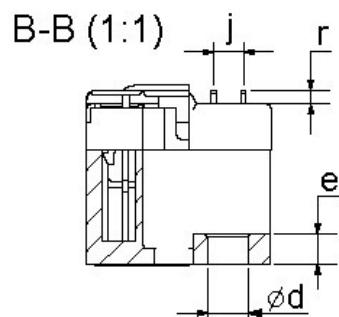
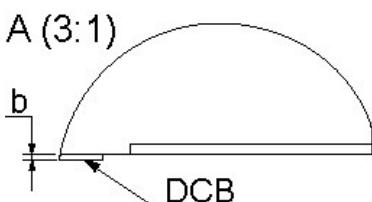
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCMA200PD1800YB	MCMA200PD1800YB	Box	6	

Equivalent Circuits for Simulation
* on die level
 $T_{VJ} = 140^\circ\text{C}$


Outlines Y4


Dim.	MIN [mm]	MAX [mm]	MIN [inch]	MAX [inch]
a	30.0	30.6	1.181	1.205
b	typ. 0.25		typ. 0.010	
c	64.0	65.0	2.520	2.559
d	6.5	7.0	0.256	0.275
e	4.9	5.1	0.193	0.201
f	28.6	29.2	1.126	1.150
g	7.3	7.7	0.287	0.303
h	93.5	94.5	3.681	3.720
i	79.5	80.5	3.130	3.169
j	4.8	5.2	0.189	0.205
k	33.4	34.0	1.315	1.339
l	16.7	17.3	0.657	0.681
m	22.7	23.3	0.894	0.917
n	22.7	23.3	0.894	0.917
o	14.0	15.0	0.551	0.591
p	typ. 10.5		typ. 0.413	
r	1.8	2.4	0.071	0.041

Optional accessories for modules

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = white, cathode = red
Type ZY 180L (L = Left for pin pair 4/5) UL758, style 3751


Thyristor

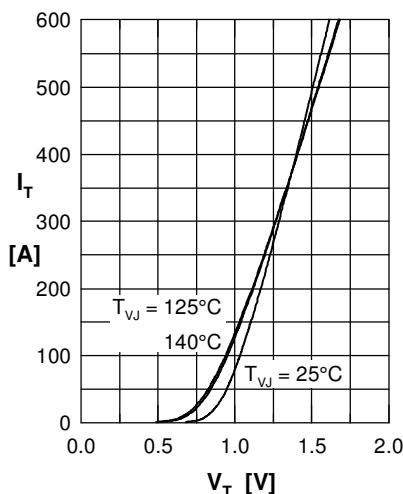


Fig. 1 Forward current vs.
voltage drop per thyristor

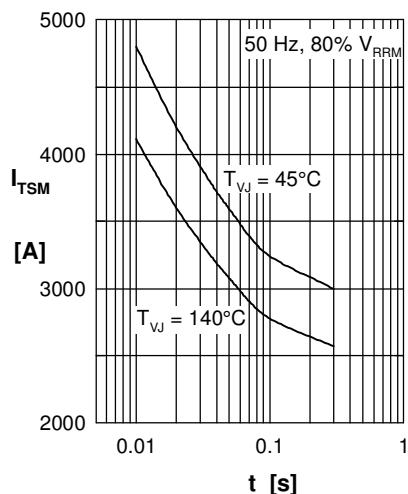


Fig. 2 Surge overload current
vs. time per thyristor

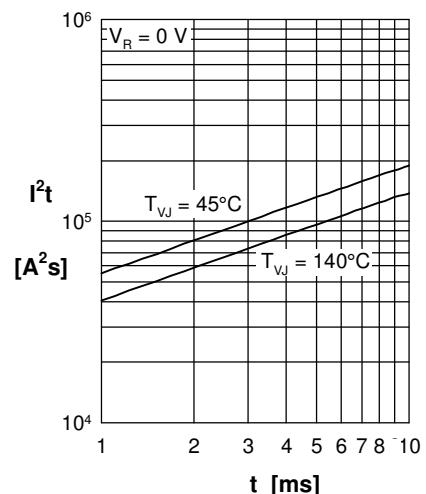


Fig. 3 I^2t vs. time per thyristor

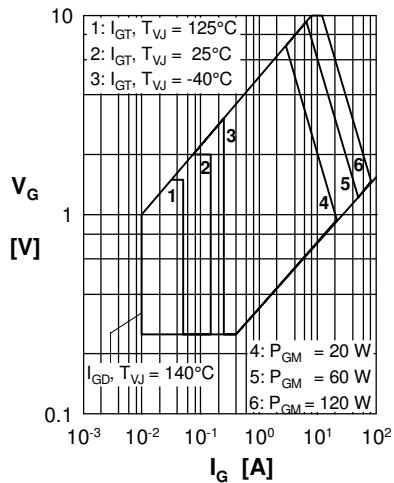


Fig. 4 Gate voltage & gate current

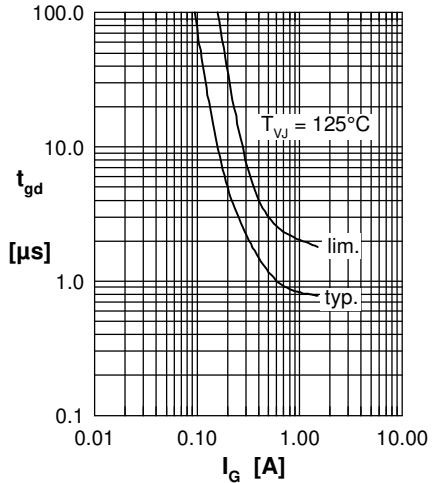


Fig. 5 Gate controlled delay time t_{gd}

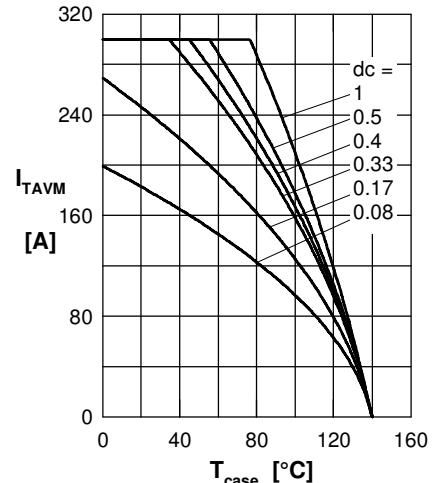


Fig. 6 Max. forward current vs.
case temperature per thy.

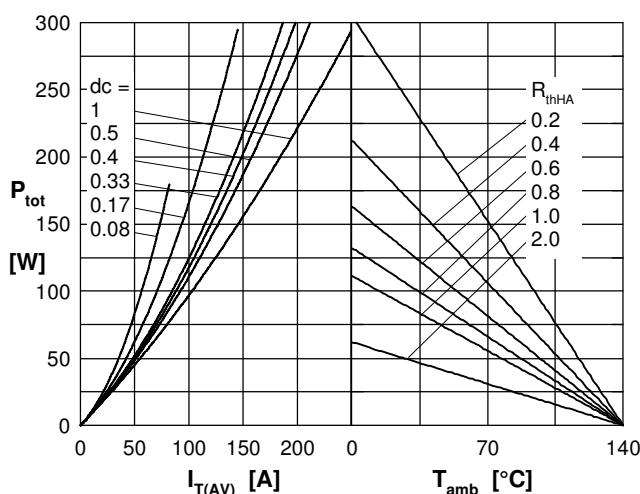


Fig. 7 Power dissipation vs. forward current
and ambient temperature per thyristor

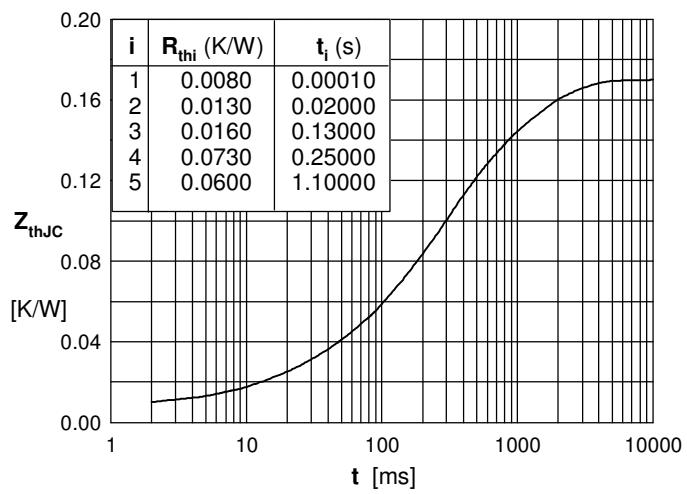


Fig. 8 Transient thermal impedance junction to case
vs. time per thyristor